

2.4GHz 1608 Chip Antenna: RANT1608F245X08

Application:

WLAN, 802.11b/g, Bluetooth, WLAN, etc...

Features

SMD, high reliability, ultra Impact, Omni-directional...

Part number Information

RANT 0603 F 245 X 08
(A) (B) (C) (D) (E) (F)

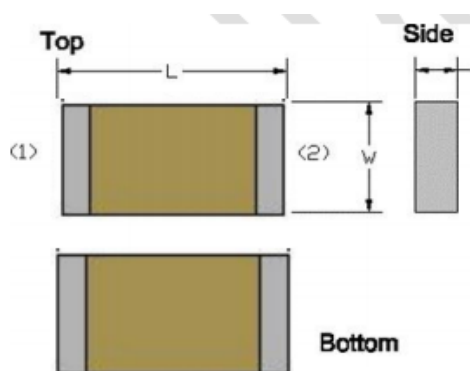
(A)Product Type	Chip Antenna
(B) Size Code	1.6x0.8mm(±0.1mm)
(C) Material	High K material
(D) Frequency	2.4 ~ 2.5GHz
(E) Feeding mode	PIFA & Single Feeding
(F) Antenna type	Type=5



Electrical Specification

Working Frequency Range	2400 ~2500 MHz
Bandwidth	120 MHz (Min.)
Peak Gain	2.7 dBi (Typ.)
Impedance	50 Ohm
Return loss	10 dB (Min)
Polarization	Linear
Azimuth Beamwidth	Omni-directional
Operation Temperature(°C)	-40 ~85°C
Resistance to Soldering Heats	10sec. (@ 280°C)
Termination	Ni / Au (Leadless)

Dimension and Terminal Configuration



Dimension (mm)	
L	1.60 ± 0.10
W	0.80 ± 0.10
T	0.45 ± 0.10

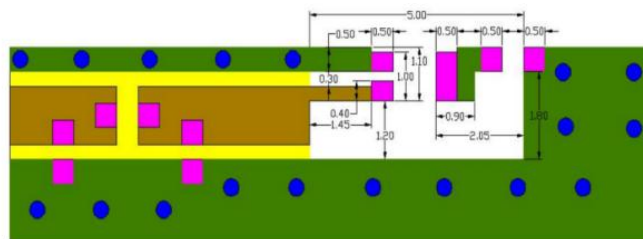
No.	Terminal Name
1	Feeding/GNG
2	GND/Feeding

咏成國際科技有限公司 RAIN International Technology Co., Ltd. TEL: 13530576606
Add:Room 707, Building F, Tongan Zhichuangyuan, xixiang street, Baoan District, Shenzhen.

咏成國際科技有限公司
RAIN International Technology Co., Ltd.

電話: 13530576606
TEL: 13530576606

PCB Dimension Unit :mm



layer:

0201 footprint (E1)

0201 footprint (E2)

0603 footprint (ANT)

3.5

1.5

1

0.5

6.5

2.5

0.5

连接微带线

连接RF I/O口

1

✓ **Layout-2 (1.5mm×10mm)**

Top layer:

Diagram illustrating the layout of a 1.5mm x 10mm board, showing dimensions and component footprints.

Dimensions:

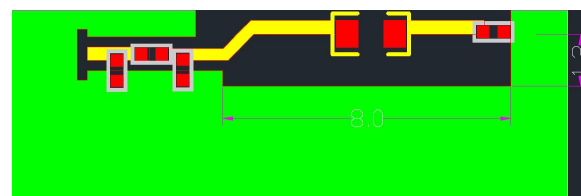
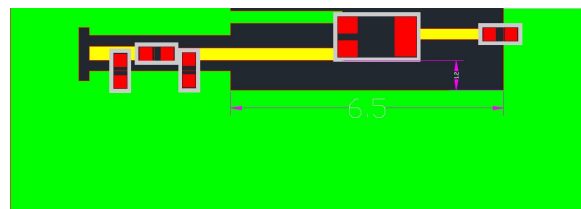
- Board size: 1.5mm x 10mm
- Top layer dimensions: 1.5mm (width), 2.5mm (distance between pads), 1.5mm (width of top pads), 10mm (height), 1.5mm (width of bottom pad), 3mm (distance from bottom edge to bottom pad), 0.5mm (width of bottom pad).

Component Footprints:

- 0201 footprint (top left)
- 0603 footprint (top right)
- 0201 footprint (bottom)

Labels:

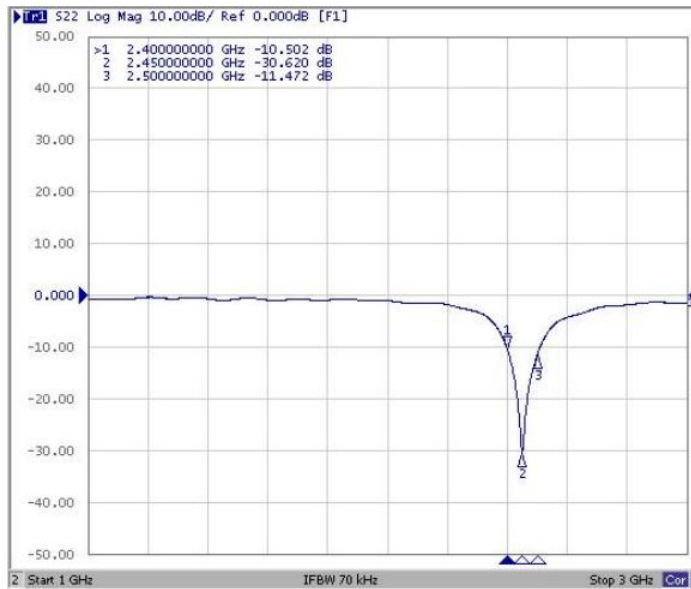
- 连接微带线, 连接RF W/O口 (Connect microstrip line, connect RF W/O port)



Electrical Characteristics

Return Loss & Radiation

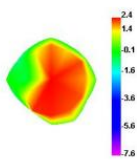
Return Loss



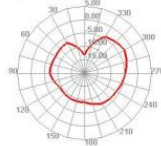
Frequency(MHz)	S11 (dB)
2400	-10.50
2450	-30.62
2500	-11.47

Radiation

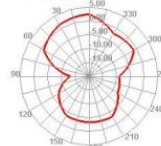
2400.000MHz



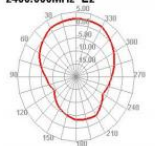
2400.000MHz H



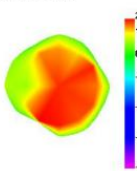
2400.000MHz E1



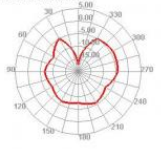
2400.000MHz E2



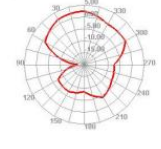
2450.000MHz



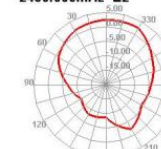
2450.000MHz H



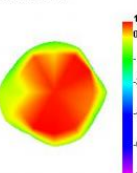
2450.000MHz E1



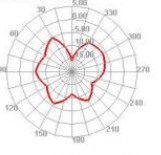
2450.000MHz E2



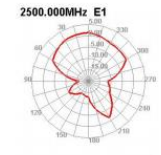
2500.000MHz



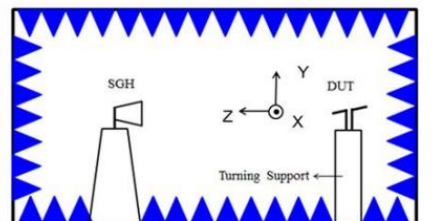
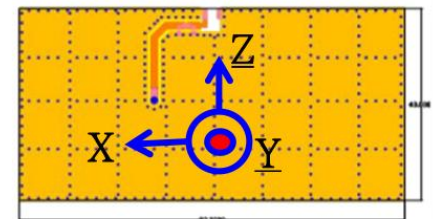
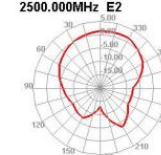
2500.000MHz H



2500.000MHz E1



2500.000MHz E2



Frequency(MHz)	2400	2450	2500
Efficiency(dB)	-0.91	-0.61	-1.01
Efficiency(%)	62	65	60
Gain(dBi)	2.4	2.7	1.5

Tester:  jiang shui ling

Taping Specifications

Reel and Taping Specification

Reel Specification

The diagram illustrates the dimensions of a 7-inch reel. It includes three views: a front view showing a circular reel with four spokes, a side view showing the thickness and dimensions A, B, C, and D, and a back view showing the central hub and spokes. The side view is labeled with a dimension of 7" x 8 mm.

TYPE	SIZE		A	B	C	D
1608	7"	4K/Reel	4.0±0.5	4.0±2	13.5±0.5	178±2

Tapping Specification

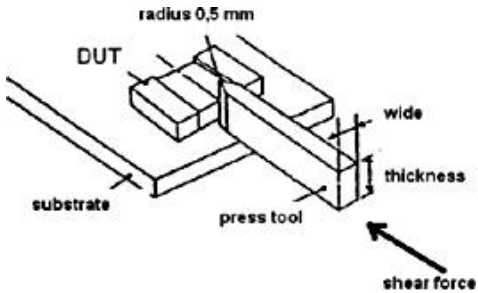
The diagram illustrates the dimensions of a chip antenna on a paper carrier. It includes a side view of the antenna with dimensions A, B, P, W, E, F, G, H, and D, and a top view of the paper carrier with dimension T. The side view shows the antenna with dimensions A, B, P, W, E, F, G, H, and D. The top view shows the paper carrier with dimension T.

Packaging	Type	A	B	W	E	F	G	H	T	ψD	P
Paper Type	1608	1.90±0.20	3.50±0.20	8.0±0.20	1.75±0.10	3.5±0.05	4.0±0.10	2.0±0.05	0.75±0.10	1.50±0.10	4.0±0.1

Reliability Table

Test Item	Procedure	Requirements Ceramic Type	Remark (Reference)
Electrical Characterization		Fulfill the electrical specification	User Spec.
Thermal Shock	1. Preconditioning: $50 \pm 10^{\circ}\text{C}$ / 1 hr , then keep for 24 ± 1 hrs at room temp. 2. Initial measure: Spec: refer Initialspec. 3. Rapid change of temperature test: -30°C to $+85^{\circ}\text{C}$; 100 cycles; 15 minutes at Lower category temperature; 15 minutes at Upper category temperature.	No Visible Damage. Fulfill the electrical specification.	MIL-STD-202 107
Temperature Cycling	1. Initial measure: Spec: refer Initialspec. 2. 100 Cycles (-30°C to $+85^{\circ}\text{C}$), Soak Mode=1 (2 Cycle/hours). 3. Measurement at 24 ± 2 Hours after test condition.	No Visible Damage. Fulfill the electrical specification.	JESD22 JA104
High Temperature Exposure	1. Initial measure: Spec: refer Initialspec. 2. Unpowered; 500hours @ $T=+85^{\circ}\text{C}$. 3. Measurement at 24 ± 2 hours after test.	No Visible Damage. Fulfill the electrical specification.	MIL-STD-202 108
Low Temperature Storage	1. Initial measure: Spec: refer Initialspec. 2. Unpowered: 500hours @ $T=-30^{\circ}\text{C}$. 3. Measurement at 24 ± 2 hours after test.	No Visible Damage. Fulfill the electrical specification.	MIL-STD-202 108
Solderability (SMD Bottom Side)	Dipping method: a. Temperature: $235 \pm 5^{\circ}\text{C}$ b. Dipping time: $3 \pm 0.5\text{s}$	The solder should cover over 95% of the critical area of bottom side.	IEC 60384-21/22 4.10
Soldering Heat Resistance (RSH)	Preheating temperature: $150 \pm 10^{\circ}\text{C}$. Preheating time: 1~2 min. Solder temperature: $260 \pm 5^{\circ}\text{C}$. Dipping time: $5 \pm 0.5\text{s}$	No Visible Damage.	IEC 60384-21/22 4.10
Vibration	5g's for 20 min., 12 cycles each of 3 orientations Note: Use 8"X5" PCB .031" thick 7 secure points on, one long side and 2 secure points at corners of opposite sides. Parts mounted within 2" from any secure point. Test from 10-2000 Hz.	No Visible Damage.	MIL-STD-202 Method 204
Mechanical Shock	Three shocks in each direction shall be applied along the three mutually perpendicular axes of the test specimen (18 shocks) Peak value: 1,500g's Duration: 0.5ms Velocity change: 15.4 ft/s Waveform: Half-sine	No Visible Damage.	MIL-STD-202 Method 213
Humidity Bias	1. Humidity: 85% R.H., Temperature: $85 \pm 2^{\circ}\text{C}$. 2. Time: 500 ± 24 hours. 3. Measurement at 24 ± 2 hrs after test condition.	No Visible Damage. Fulfill the electrical specification.	MIL-STD-202 Method 106

2.4GHz 1608 Chip Antenna: RANT0603F245S5

Board Flex (SMD)	1. Mounting method: IR-Reflow. PCB Size (L:100 × W:40 × T:1.6mm) 2. Apply the load in direction of the arrow until bending reaches 2 mm.	No Visible Damage.	AEC-Q200 005
Adhesion	Force of 1.8Kg for 60 seconds. 	No Visible Damage Magnification of 20X or greater may be employed for inspection of the mechanical integrity of the device body terminals and body/terminal junction.	AEC-Q200 006
Physical Dimension	Any applicable method using x10 magnification, micrometers, calipers, gauges, contour projectors, or other measuring equipment, capable of determining the actual specimen dimensions.	In accordance with specification.	JESD22 JB100

Revision History

Revision	Date	Content
1	2019/03/01	New Datasheet
2	2020/02/22	Add 2D radiation characteristic